

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Examiner: Cathy Lam

Kwun Yao Ho et al.

Serial No.: 10/717,116

Art Unit: 1775

Filed: 11/19/2003

Title: Lamination Process and Structure of High Layout Density Substrate

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

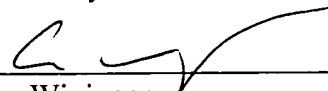
**INTERVIEW SUMMARY**

Applicants' undersigned representative held telephonic interviews with the Examiner on March 15 and 17. Examiner requested clarification of the claim language and clarified claim language was agreed upon as indicated by the Examiner's amendment. Claims 31 – 35 were cancelled because of the Examiner's concern for structural indefiniteness and to enable the application to issue quickly.

The undersigned authorizes any fees which may be required, or credit any overpayment to Deposit Account No. 05-0150. Should the Examiner have any questions regarding this communication, the Examiner is invited to contact the undersigned at the telephone number shown below.

Date: 4/15/05  
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Respectfully submitted,

  
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**CERTIFICATE OF MAILING**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

Date: 4-15-05 By:   
Eileen Janikowski